

DS99R421 EVM  
TIDA-00136

Item	Qty	Reference	Part	PCB Footprint	Comments	NO-STUFF
1	2	C1,C2	0.1uF	CAP/HDC-0402	CAP .1UF 10V CERAMIC X5R 0402	
2	1	C3	22uF	CAP/N	CAP TANTALUM 22UF 25V 20% SMD	
3	1	C4	2.2uF	3528-21_EIA	CAPACITOR TANT 2.2UF 20V 10% SMD	
4	1	C5	0.1uF	CAP/HDC-1206	CAP .10UF 50V CERAMIC X7R 1206	
5	4	C6,C11,C14,C17	22uF	CAP/EIA-B 3528-21	CAPACITOR TANT 22UF 16V 20% SMD	
6	4	C7,C10,C13,C16	0.1uF	CAP/HDC-0603	CAP .1UF ±10% 25V CERAMIC X7R 0603	
7	4	C8,C9,C12,C15	0.01uF	CAP/HDC-0603	CAP CERAMIC .01UF 100V X7R 0603	
8	4	JP1,JP2,JP3,JP4	2-Pin Header_open	Header/2P	CONN HEADER VERT .100 2POS 30AU. DO NOT PURCHASE, DO NOT LOAD.	No-stuff
9	2	JP8,JP5	3-Pin Header	Header/3P	CONN HEADER VERT .100 3POS 15AU	
10	1	JP6	2-Pin Header	Header/2P	CONN HEADER VERT .100 2POS 30AU	
11	1	JP7	2X3-Pin Header	Header/2X3P	CONN HEADER .100 DUAL STR 6POS.	
12	1	JP9	2X12-Pin Header, open	Header/2X12P	CONN HEADER .100 DUAL STR 24POS. DO NOT PURCHASE, DO NOT LOAD.	No-stuff
13	1	JP10	2X10-Pin Header, open	Header/2X10P	CONN HEADER .100 DUAL STR 20POS. DO NOT PURCHASE, DO NOT LOAD.	No-stuff
14	1	J1	2X10-Pin Header	Header/2X10P	CONN HEADER 20 POS STRGHT GOLD.	
15	1	J2	2mm_2X5_open	CON/HDR-10P-B	Female connector with solder pins 2,9. har_Link, DS_link. DO NOT PURCHASE, DO NOT MOUNT.	No-stuff
16	2	J4,J3	BANANA	CON/BANANA-S	BANANA-female (non-insulated)	
17	1	P1	mini USB 5pin_open	mini_B_USB_surface_mount	CONN RECEPT MINI USB2.0 5POS. DO NOT PURCHASE, DO NOT MOUNT.	No-stuff
18	1	P2	RJ-45 8pin_open	RJ-45_thru_hole	Subminiature, LAN Modular Jack Connectors TM11R-5M2 Series 8POS. DO NOT PURCHASE, DO NOT MOUNT.	No-stuff
19	1	P3	USB A	USB_TYPE_A_4P	CONN USB RECEPT R/A TYPE A 4POS.	
20	4	R1,R2,R3,R4	100ohm,0201_open	RES/HDC-0201	RES 100 OHM 1/20W 1% 0201 SMD. DO NOT PURCHASE DO NOT LOAD.	No-stuff
21	1	R5	100 ohm,0402	RES/HDC-0402	RES 100 OHM 1/16W 1% 0402 SMD.	
22	1	R6	5.76K	RES/HDC-0402	RES 5.76K OHM 1/16W 1% 0402 SMD	
23	4	R7,R8,R9,R10	10K_open	RES/HDC-0805	1% Precision Thick Film Chip Res; 1/10W. DO NOT PURCHASE, DO NOT LOAD.	No-stuff
24	4	R11,R12,R13,R14	0 ohm	RES/HDC-0201	RES 0.0 OHM 1/20W 5% 0201 SMD	
25	4	R15,R16,R17,R18	0 Ohm,0402	RES/HDC-0402	RES ZERO OHM 1/16W 5% 0402 SMD	
26	4	R19,R20,R21,R22	10K	RES/HDC-0805	1% Precision Thick Film Chip Res; 1/10W	
27	1	S1	SW DIP-4	DIP-8	SWITCH DIP EXTENDED SEALED 4POS	
28	1	U1	DS99R421	36 Id LLP	DS99R421QSQ 4-channel LVDS converter to single LVDS embedded clock SERDES	
29	1	VR1	SVR20K	Surface Mount 4mm Square	11-Turn Trimming Potentiometer; Top Adjust	
30	2	X2,X1	TP_0402	TP/0402	0402 test pad. NOT A COMPONENT.	

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